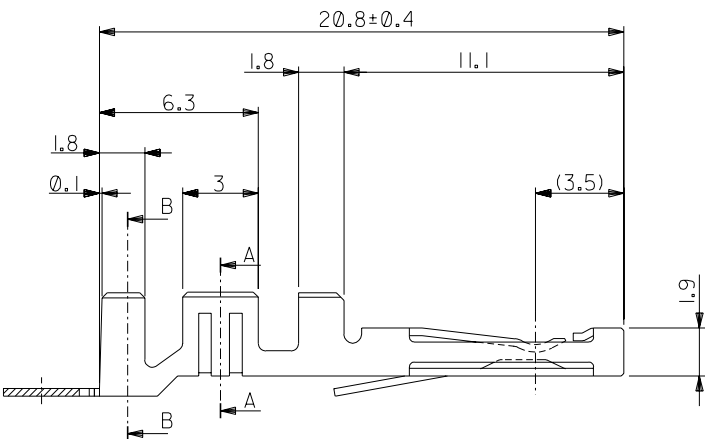
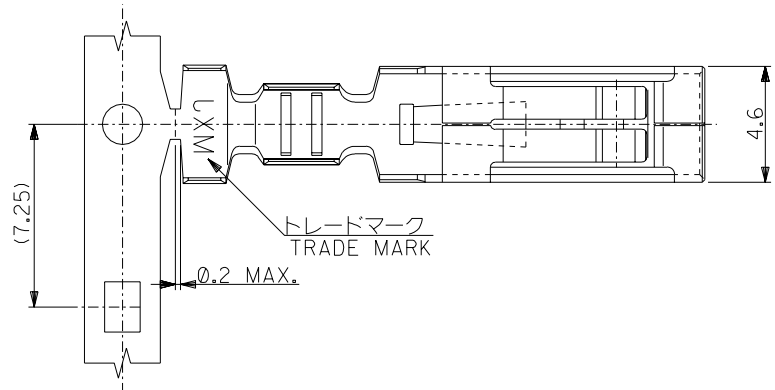


注)
NOTES:

- 材質
MATERIAL
銅合金 (板厚: 0.3)
COPPER ALLOY (THICKNESS: 0.3)
- メッキ仕様
TERMINAL PLATING
接点部 : 金メッキ 0.25 μm MIN.
CONTACT AREA : GOLD 0.25 MICROMETER MIN.
圧着部 : 錫メッキ 1.0 μm MIN.
CRIMP AREA : TIN 1.0 MICROMETER MIN.
下地メッキ : ニッケルメッキ 2.0 μm MIN.
UNDER PLATE : NICKEL 2.0 MICROMETER MIN.
- 適用電線範囲 : UL 2517, AWG #16
APPLICABLE WIRE RANGE : UL2517, AWG #16
- 被覆外径 : φ2.2~φ2.7
INSULATION EXTERNAL DIA : φ2.2~φ2.7
- 適用ハウジングアッセンブリ : 51195 シリーズ
APPLICABLE HOUSING ASS'Y : 51195 SERIES
- 本製品は59319-**-90の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 59319-**-90.

バラ状 LOOSE	59319-0128	59319-**-28
連鎖状 CHAIN	59319-0028	
端子形状 TERMINAL CONFIGURATION	MATERIAL No.	MODEL No.

EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		RELEASED EC NO. J2004-3411 DRWN: Y.WADA '04/03/29 CHK: M.SASAO '04/03/29 APPR: M.SASAO '04/03/29		DESCRIPTION 仕上り	MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 1:1	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	☐ mm INCH	☐ INCH mm	☒ mm ONLY	REVISE ON CAD ONLY					
													10 UNDER 未満	±0.2	DRAWN BY & DATE Y.WADA '04/03/29		TITLE: POWER CONN. REC. CRIMP TERMINAL -LEAD FREE-									
													10 OVER 以上	30 UNDER 未満	±0.25	CHECKED BY & DATE M.SASAO '04/03/29										
														30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/03/29		MOLEX INCORPORATED								
														ANGLE 角度	±3°	CAD FILENAME SD-59319-002.S01								MATERIAL NO. SEE CHART		DRAWING NO. SD-59319-002
								0	REV	INS. RANGE 被覆外径						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.										SIZE B